

TQFP Thin Profile Quad Flat Pack

Highlights

- 10 x 10mm to 16 x 16mm
- 44 to 144 lead count
- Lead pitch range from 0.50mm to 0.40mm



Features

- Body Sizes: 10 x 10mm to 16 x 16mm
- Package Height: 1.0mm
- Lead Counts: 44L to 144L
- Lead Pitch: 0.50mm to 0.40mm
- Available in gold or copper wirebond versions
- Limited number of open tool leadframe and die pad sizes available
- JEDEC standard compliant
- Lead-free, Green and Low Alpha materials sets available

Description

The Thin Profile Quad Flat Pack (TQFP) belongs to our QFP offering. At 1.0mm body thickness, the TQFP is the thinnest package in the QFP family. This thin package is made possible by a well controlled low loop wire bonding process and package warpage control during the molding process.

We also offer the TQFP in an Exposed Pad configuration (TQFP-ep). This is a thermally enhanced version of the TQFP package. Thermal enhancement is achieved by means of an exposed die pad, which can be soldered to a mother PC board for effective heat removal and grounding, if needed. This enhanced thermal package is made possible by a deep downset die pad leadframe design.

TQFP is suitable for mainstream cost sensitive applications where thickness and weight are premium.

Applications

- ASIC
- DSP
- Gate Array
- Logic IC
- Microprocessors
- Microcontrollers
- Multimedia
- PC Chipsets

Specifications

Die Thickness	230-280µm (9-11mils) range preferred
Wire	
Gold:	18-30μm (0.7-1.2mils) diameter
Copper:	18-30μm (0.7-1.2mils) diameter
Lead Finish	Matte Tin
Marking	Laser
Packing Options	Tape & reel, tube, JEDEC tray

Reliability

Moisture Sensitivity Level	JEDEC Level 3
Temperature Cycling	-65°C/150°C, 1000 cycles
High Temperature Storage	150°C, 500 hrs
Pressure Cooker Test	121°C, 100% RH, 2 atm, 168 hrs
Liquid Therapy Shock (opt)	-55°C/125°C, 1000 cycles

TQFP Thermal Performance θ ja (°C/W)

Package Body Size		Pad Size	Die Size	Thermal Performance
Size (mm)		(mm)	(mm)	θja (C/W)
100L	14 x 14 x 1.0	9.0 x 9.0	7.8 x 7.8	

Note: Simulation data for package mounted on 4 layer PCB (per JEDEC JESD51-7) under natural convection as defined in JESD51-2.

TQFP-ep Thermal Performance θja (°C/W)

Package	Body Size	Pad Size	Die Size	PCB	Thermal Performance
Size	(mm)	(mm)	(mm)	Vias	θja (C/W)
80L	12 x 12 x 1.0	7.2 x 7.2	6.0 x 6.0	36	

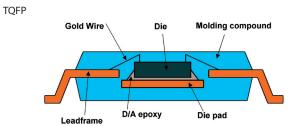
Note: Simulation data for package mounted on 4 layer PCB (per JEDEC JESD51-7) under natural convection as defined in JESD51-2. Based on TQFP-ep simulations.

Electrical Performance

Electrical parasitic data is highly dependent on the package layout. 3D electrical simulation can be used on the specific package design to provide the best prediction of electrical behavior. Data below is for a frequency of 100MHz and assumes 1.0 mil gold bonding wire.

Conductor Component	Length (mm)	Resistance (mOhms)	Inductance (nH)	Mutal Inductance (nH)	Capacitance (pF)	Capacitance Mutual (pF)
Wire	2	120	1.65	0.45 - 0.85	0.10	0.01 - 0.02
Lead (14 x 14mm, 128L)	3.0 - 4.5	24.0 - 36.0	1.96 - 2.92	1.08 - 1.61	0.45 - 0.67	0.20 - 0.30
Total (14 x 14mm, 128L)		144.0 - 156.0	3.61 - 4.57	1.53 - 2.46	0.55 - 0.77	0.21032

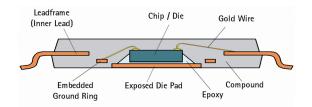
Cross Sections



Package Configurations

Package	Size (mm)	Lead Count
TQFP	10 x 10	44
	12 x 12	80
	14 x 14	128
	16 x 16	144
TQFP-ep	10 x 10	44
	12 x 12	80
	14 x 14	128
	16 x 16	144

TQFP-ep





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